Product Change Notification

112214 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**112214 - 00**
Change Title:	**Pedestal Chassis Hot Swap Drive Kit FUP4X35HSDK and Spare Hot Swap Backplane FUP4X35HSBP** **PCN 112214-00, Product Design, Label Update Hot-swap Backplane (HSBP) and HSBP Firmware**
Date of Publication:	**April 25, 2013**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	May 25, 2013

Description of Change to the Customer:

Intel will implement the following change on the Pedestal Chassis Hot Swap Drive Kit FUP4X35HSDK and Spare Hot Swap Backplane FUP4X35HSBP:

- The four drive 3.5” Hot-swap Backplane (HSBP) is being updated from Printed Board Assembly (PBA) G15583-301 to G15583-303. This change is to update the HSBP firmware to include the Field Replaceable Unit (FRU) information.

Note: As a result of this change, the TA (top assembly) numbers will roll as noted in the affected products table within this PCN notice. If the TA numbers are printed on any product or box labels, those will show the TA dash roll as well.

Customer Impact of Change and Recommended Action:

Intel expects no impact to customers from these changes, but encourages customers to understand the changes and determine impact to their applications.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
FUP4X35HSDK	911885	G21449-003	G15583-301	G21449-004	G15583-303
FUP4X35HSBP	913595	G26526-001	G15583-301	G26526-002	G15583-303

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 25, 2013	00	Originally Published PCN